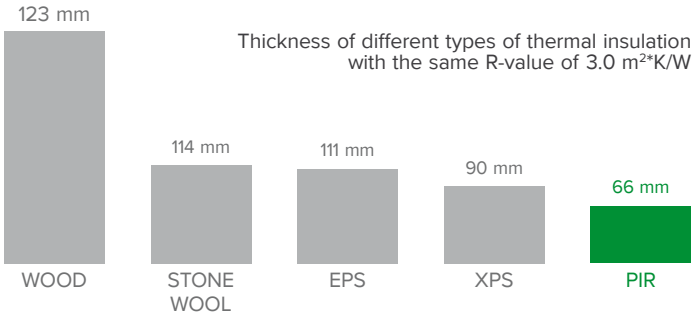
TECHNONICOL

LOGICPIR

THERMAL INSULATION BOARD

LOGICPIR is an innovative thermal insulation board made of PIR (Polyisocyanurate), which is used in flat and pitched roofing systems, floors, walls and facades. Being very rigid and perfectly flat, LOGICPIR is an ideal substrate for roofing materials. It has high compressive strength and a record low thermal conductivity value.

More than 95% of LOGICPIR board consists of closed rigid cells. The material does not absorb water and does not burn. It maintains stable parameters for a long period of time.



Thickness of different types of thermal insulation with the same R-value of 3.0 m²*K/W

TECHNICAL DATA

PROPERTIES	PERFORMANCE
Surface type	aluminium foil / fiberglass mat
Thermal conductivity, W/m*K	0.022 / 0.026
Compressive stress, kPa	≥150
Long term water absorption, %	≤1
Reaction to fire, Euroclass	E
Board sizes, mm	1200×600, 2400×1200
Thickness, mm	30-150 (increments 10 mm)

LOGICPIR
with aluminium foil covering

LOGICPIR
with fiberglass covering

UNIQUE FEATURES OF LOGICPIR

RELIABILITY AND DURABILITY

Throughout its 50-year service life, LOGICPIR retains its qualities. It functions effectively within a temperature range from -65°C to +110°C being suitable for any climate.

HIGH FIRE RESISTANCE

LOGICPIR is a non-flammable material. When in contact with an open flame, polymer burns on the surface only. This creates a charcoal skin, which is an effective defence against further polymer damaging.

DYNAMIC LOAD RESISTANCE

LOGICPIR complies with class 2 for the dynamic load (EN 826). Compressive strength of 150 kPa provides high resistance against deformation due to operation loads.

RECORD-LOW THERMAL CONDUCTIVITY

LOGICPIR has a record-low thermal conductivity starting from 0.022 W/m*K. Boards have L-shaped edges, so they fit tightly together and thus prevent thermal bridges.

LIGHTWEIGHT

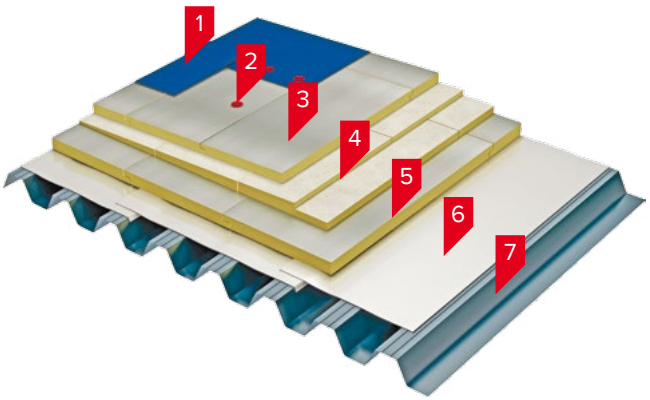
The use of LOGICPIR reduces the overall weight of the construction. This is especially important for roofs renovation. Transportation costs are substantially reduced as well.

MINIMAL WATER ABSORPTION

The board structure consists of closed rigid cells, which do not allow water to come into the material. The composite facers provide an additional vapor barrier.

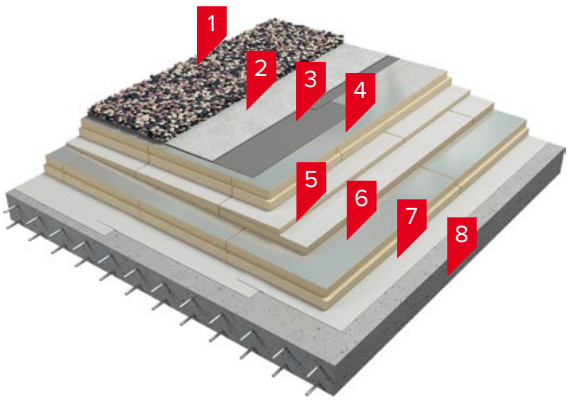
ROOFING SYSTEMS

MECHANICALLY FIXED ROOFING SYSTEM



1. PVC membrane LOGICROOF V-RP
2. Mechanical fixation
3. Thermal insulation board LOGICPIR
4. Thermal insulation board LOGICPIR Slope
5. Thermal insulation board LOGICPIR
6. Vapor barrier VAPORSTOP CA 500
7. Corrugated steel sheet

BALLASTED ROOFING SYSTEM



1. Ballast
2. Geotextile 300 g/m²
3. PVC membrane LOGICROOF V-GR
4. Thermal insulation board LOGICPIR
5. Thermal insulation board LOGICPIR Slope
6. Thermal insulation board LOGICPIR
7. Vapor barrier VAPORSTOP CA 500
8. Reinforced concrete base

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